

CFD6001P

**SURFACE MOUNT SILICON
ULTRA LOW LEAKAGE
ANTI-PARALLEL DIODE**



www.centrasemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CFD6001P consists of two (2) ultra low leakage diodes in an anti-parallel configuration. The device package has a very small footprint and low profile, making it ideal for energy sensitive, space constrained applications.

MARKING CODE: 1P



APPLICATIONS:

- DC-DC converters
- Voltage clamping
- Protection circuits
- Mixer circuits

FEATURES:

- Current ($I_F=250\text{mA}$)
- Forward Voltage Drop ($V_F=1.1\text{V MAX @ }100\text{mA}$)
- SOD-882L Surface Mount Package

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Continuous Forward Current
Peak Forward Surge Current, $t_p=1.0\mu\text{s}$
Peak Forward Surge Current, $t_p=1.0\text{s}$
Power Dissipation
Operating and Storage Junction Temperature
Thermal Resistance

SYMBOL

I_F 250
 I_{FSM} 4.0
 I_{FSM} 1.0
 P_D 100
 T_J, T_{stg} -65 to +150
 Θ_{JA} 1250

UNITS

mA
A
A
mW
 $^\circ\text{C}$
 $^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS PER DIODE: ($T_A=25^\circ\text{C}$ unless otherwise noted)

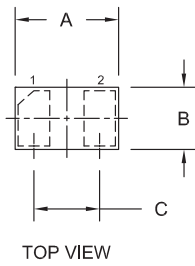
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
V_F	$I_F=1.0\text{mA}$		0.85	V
V_F	$I_F=10\text{mA}$		0.95	V
V_F	$I_F=100\text{mA}$		1.1	V
C_J	$V_R=0, f=1.0\text{MHz}$		6.0	pF

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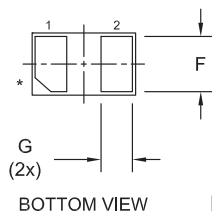
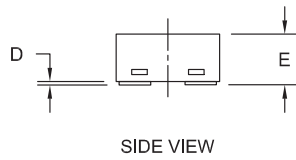


SOD-882L CASE - MECHANICAL OUTLINE



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.037	0.041	0.95	1.05
B	0.022	0.026	0.55	0.65
C	0.026		0.65	
D	0.000	0.002	0.00	0.05
E	0.012	0.016	0.30	0.40
F	0.018	0.022	0.45	0.55
G	0.008	0.012	0.20	0.30

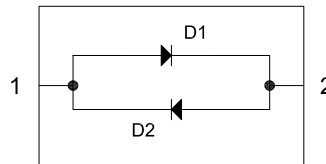
SOD-882L (REV:R2)



* Pin 1 chamfer may appear on any corner.

R2

PIN CONFIGURATION



LEAD CODE:

- 1) Anode D1, Cathode D2
- 2) Cathode D1, Anode D2

MARKING CODE: 1P

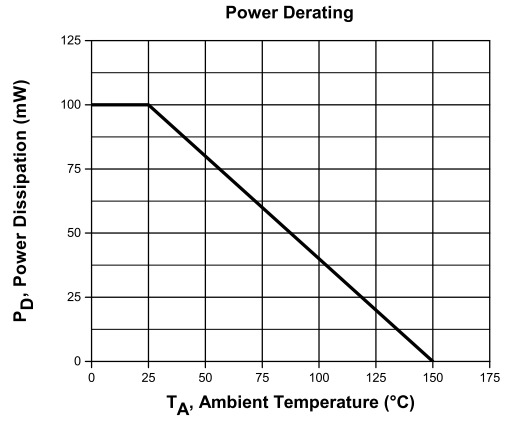
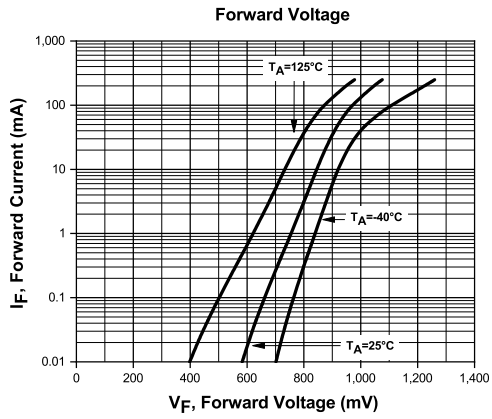
R2 (14-March 2018)

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TYPICAL ELECTRICAL CHARACTERISTICS



R2 (14-March 2018)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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